

Please replace the paragraph beginning at page 13, line 8, with the following rewritten paragraph:

--I. Introduction

The vertically-connected stripline structure described herein comprises a stack of substrate layers. A substrate "layer" is defined as a substrate including circuitry on one or both sides. A process for constructing such a multilayer structure is disclosed by U.S. Patent Application No. 09/199,675 entitled "Method of Making Microwave, Multifunction Modules Using Fluoropolymer Composite Substrates", filed November 25, 1998, now U.S. Patent No. 6,099,977 to Logothetis et al., incorporated herein by reference. Note that references to "substrate layer" and "metal layer" herein are often referred to as "layer" and "metalization", respectively, in U.S. Patent No. 6,099,977.-

In the claims:

Please cancel claims 1-8 and 17-24 without prejudice.

CONDITIONAL PETITION FOR EXTENSION OF TIME

If any extension of time for this response is required, applicant requests that this be considered a petition therefore. Please charge the required Petition fee to Deposit Account No. 03-1240.

ADDITIONAL FEE

Please charge any insufficiency of fees, or credit any excess to our Deposit Account No. 03-1240.